

# **C4D02120A**Silicon Carbide Schottky Diode

## Z-Rec® Rectifier

 $V_{RRM} = 1200 V$   $I_{F} (T_{c}=135^{\circ}C) = 6 A$   $Q_{c} = 12 nC$ 

#### **Features**

- 1.2kV Schottky Rectifier
- Zero Reverse Recovery Current
- High-Frequency Operation
- Temperature-Independent Switching
- Extremely Fast Switching

### **Benefits**

- Replace Bipolar with Unipolar Rectifiers
- Essentially No Switching Losses
- Higher Efficiency
- Reduction of Heat Sink Requirements
- Parallel Devices Without Thermal Runaway

## **Applications**

- Switch Mode Power Supplies
- Power Factor Correction
- Motor Drives

## **Package**







TO-220-2



Part Number	Package	Marking	
C4D02120A	TO-220-2	C4D02120	

## **Maximum Ratings** (T<sub>c</sub>=25°C unless otherwise specified)

Symbol	Parameter	Value	Unit	Test Conditions	Note
$V_{RRM}$	Repetitive Peak Reverse Voltage	1200	٧		
$V_{\scriptscriptstyle RSM}$	Surge Peak Reverse Voltage	1300	V		
$V_R$	DC Peak Reverse Voltage	1200	V		
$I_{_{\rm F}}$	Continuous Forward Current	10 5 2	А	T <sub>c</sub> =25°C T <sub>c</sub> =135°C T <sub>c</sub> =165°C	
$\mathbf{I}_{FRM}$	Repetitive Peak Forward Surge Current	13 8.4	А	$T_c$ =25°C, $t_p$ =10 ms, Half Sine Pulse $T_c$ =110°C, $t_p$ =10 ms, Half Sine Pulse	
$\mathbf{I}_{FSM}$	Non-Repetitive Forward Surge Current	19 16.5	Α	$T_c$ =25°C, $t_p$ =10 ms, Half Sine Pulse $T_c$ =110°C, $t_p$ =10 ms, Half Sine Pulse	
$\mathbf{I}_{\text{F,Max}}$	Non-Repetitive Peak Forward Current	200 160	А	$T_c$ =25°C, $t_p$ =10 $\mu$ s, Pulse $T_c$ =110°C, $t_p$ =10 $\mu$ s, Pulse	
P <sub>tot</sub>	Power Dissipation	60 26	W	T <sub>c</sub> =25°C T <sub>c</sub> =110°C	
Т	Operating Junction Range	-55 to +175	°C		
$T_{stg}$	Storage Temperature Range	-55 to +135	°C		
	TO-220 Mounting Torque	1 8.8	Nm lbf-in	M3 Screw 6-32 Screw	



## **Electrical Characteristics**

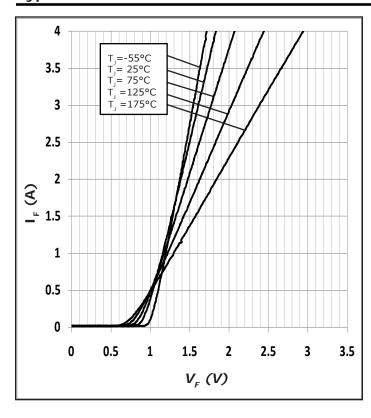
Symbol	Parameter	Тур.	Max.	Unit	Test Conditions	Note
V <sub>F</sub>	Forward Voltage	1.4 1.9	1.8 3	V	$I_F = 2 \text{ A } T_J = 25^{\circ}\text{C}$ $I_F = 2 \text{ A } T_J = 175^{\circ}\text{C}$	
$I_R$	Reverse Current	10 40	50 150	μΑ	V <sub>R</sub> = 1200 V T <sub>J</sub> =25°C V <sub>R</sub> = 1200 V T <sub>J</sub> =175°C	
Q <sub>c</sub>	Total Capacitive Charge	11		nC	$V_R = 800 \text{ V, } I_F = 2A$ $di/dt = 200 \text{ A/}\mu\text{s}$ $T_J = 25^{\circ}\text{C}$	
С	Total Capacitance	167 11 8		pF	V <sub>R</sub> = 0 V, T <sub>J</sub> = 25°C, f = 1 MHz V <sub>R</sub> = 400 V, T <sub>J</sub> = 25°C, f = 1 MHz V <sub>R</sub> = 800 V, T <sub>J</sub> = 25°C, f = 1 MHz	

#### Note:

## **Thermal Characteristics**

Symbol	Parameter	Тур.	Max.	Unit	Test Conditions	Note
$R_{\theta JC}$	Thermal Resistance from Junction to Case	2.5		°C/W		

## **Typical Performance**





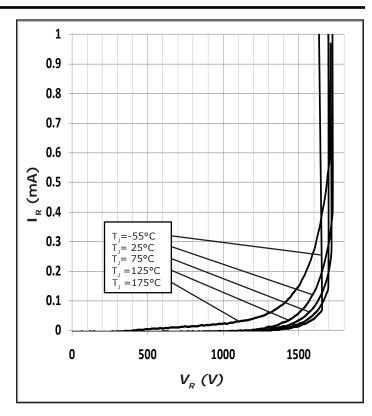
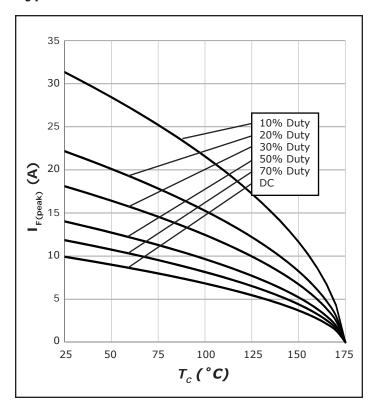


Figure 2. Reverse Characteristics

<sup>1.</sup> This is a majority carrier diode, so there is no reverse recovery charge.



## **Typical Performance**



 $P_{Tot}$  (W)  $T_c$  (°C)

Figure 3. Current Derating

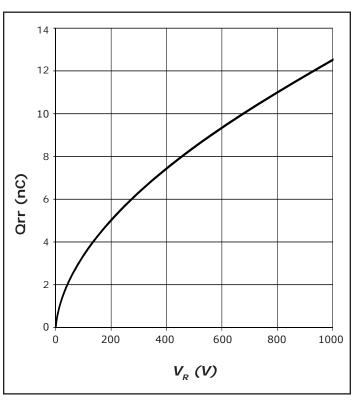


Figure 5. Recovery Charge vs. Reverse Voltage

Figure 4. Power Derating

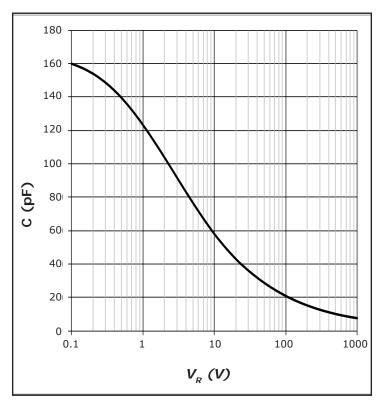
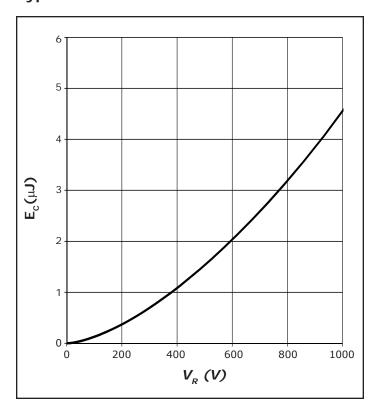


Figure 6. Capacitance vs. Reverse Voltage



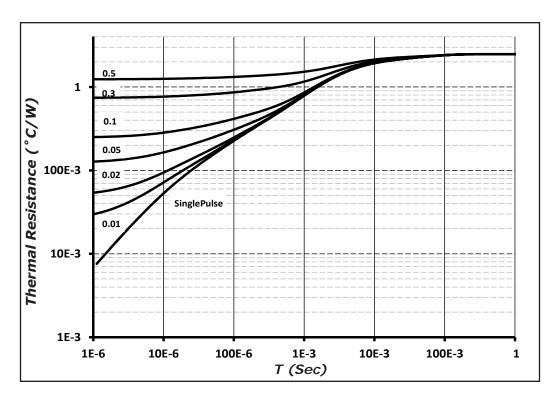
## **Typical Performance**



 $\underbrace{\mathbf{Z}}_{\mathbf{L}} = 100$   $\underbrace{\mathbf{T}_{\mathbf{J}} = 25^{\circ}\mathbf{C}}_{\mathbf{T}_{\mathbf{J}} = 110^{\circ}\mathbf{C}} = 110^{\circ}\mathbf{C}$   $\underbrace{\mathbf{t}_{\rho} (\mathbf{s})}_{\mathbf{L}} = \mathbf{L}_{\mathbf{L}} = \mathbf{L}_{\mathbf{L}}$ 

Figure 7. Typical Capacitance Stored Energy

Figure 8. Non-repetitive peak forward surge current versus pulse duration (sinusoidal waveform)



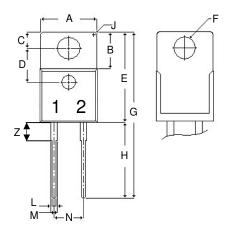
1000

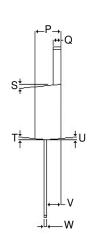
Figure 9. Transient Thermal Impedance



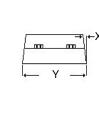
## **Package Dimensions**

Package TO-220-2







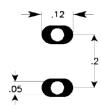


	POS	Inc	hes	Millimeters		
	PUS	Min	Max	Min	Max	
	А	.381	.410	9.677	10.414	
	В	.235	.255	5.969	6.477	
	С	.100	.120	2.540	3.048	
	D	.223	.337	5.664	8.560	
	E	.590	.615	14.986	15.621	
(	F	.143	.153	3.632	3.886	
	G	1.105	1.147	28.067	29.134	
	Н	.500	.550	12.700	13.970	
	J	R 0.	197	R 0.197		
	L	.025	.036	.635	.914	
	М	.045	.055	1.143	1.397	
	N	.195	.205	4.953	5.207	
	Р	.165	.185	4.191	4.699	
	Q	.048	.054	1.219	1.372	
	S	3°	6°	3°	6°	
	Т	3°	6°	3°	6°	
	U	3°	6°	3°	6°	
	V	.094	.110	2.388	2.794	
	W	.014	.025	.356	.635	
	Х	3°	5.5°	3°	5.5°	
	Υ	.385	.410	9.779	10.414	
	z	.130	.150	3.302	3.810	
	NOTE:	•				

#### NOTE:

 Dimension L, M, W apply for Solder Dip Finish

## **Recommended Solder Pad Layout**



TO-220-2

Part Number	Package	Marking		
C4D02120A	TO-220-2	C4D02120		

Note: Recommended soldering profiles can be found in the applications note here: http://www.cree.com/power\_app\_notes/soldering





#### **Diode Model**

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$$V_{fT} = V_T + If * R_T$$

$$V_T = 0.9592 + (T_J^* -1.20^*10^{-3})$$
  
 $R_T = 0.1673 + (T_J^* 2.10^*10^{-3})$ 

Note: T<sub>J</sub> = Diode Junction Temperature In Degrees Celsius

#### **Notes**

#### RoHS Compliance

The levels of RoHS restricted materials in this product are below the maximum concentration values (also referred to as the threshold limits) permitted for such substances, or are used in an exempted application, in accordance with EU Directive 2011/65/EC (RoHS2), as implemented January 2, 2013. RoHS Declarations for this product can be obtained from your Cree representative or from the Product Documentation sections of www.cree.com.

#### REACh Compliance

REACh substances of high concern (SVHCs) information is available for this product. Since the European Chemical Agency (ECHA) has published notice of their intent to frequently revise the SVHC listing for the foreseeable future, please contact a Cree representative to insure you get the most up-to-date REACh SVHC Declaration. REACh banned substance information (REACh Article 67) is also available upon request.

• This product has not been designed or tested for use in, and is not intended for use in, applications implanted into the human body nor in applications in which failure of the product could lead to death, personal injury or property damage, including but not limited to equipment used in the operation of nuclear facilities, life-support machines, cardiac defibrillators or similar emergency medical equipment, aircraft navigation or communication or control systems, or air traffic control systems.

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